Claim Amendments

This listing of the claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (currently amended): A production method, which comprises the steps of:

providing a motor vehicle molding for producing an end product selected from the group consisting of doors, door modules, door panels, dashboard parts, and dashboards;

treating a surface of the motor vehicle molding selectively in a manner corresponding to a profile provided for a conductor run, ~~such that~~ causing the profile for the conductor run to have a higher adhesion than the surface without the profile for the conductor run ~~surface has areas of different adhesion~~ by performing one of the steps of:

coating the surface with a substance to be cross-linked, the substance having an adhesion characteristic varied by subsequent locally selective cross-linking;

coating the surface with a substance to be cured, the substance having an adhesion characteristic varied by subsequent locally selective curing;

applying a chemically active substance varying an adhesion characteristic of the surface;

treating the surface by supplying heat;

electrostatically charging the surface; and

selectively applying an adhesion layer to the surface;

applying a germination layer to the profile provided for the conductor run with the higher adhesion, by one of the steps of applying a powder to the surface and drawing the motor vehicle molding through a powder bath, causing the powder to only adhere to the profile provided for the conductor run; and

applying the conductor run to the germination layer resulting in the conductor run being integrally connected to the motor vehicle molding.

Claim 2 (currently amended): The method according to claim 1, which further comprises applying the conductor run using a thermal spraying as a beam thermal/kinetic application method.

Claim 3 (withdrawn): The method according to claim 2, which further comprises using an inert gas as a carrier gas for a particle beam for the beam thermal/kinetic application method.

Claim 4 (withdrawn): The method according to claim 3, which further comprises adding conductive particles and nonconductive impurities to the particle beam.

Claim 5 (original): The method according to claim 1, which further comprises applying the conductor run from a melt, and the motor vehicle molding being drawn together with the germination layer through a melt bath to apply the conductor run.

Claim 6 (original): The method according to claim 1, which further comprises carrying out at least two of the method steps using one processing apparatus.

Claims 7 and 8 (cancelled).

Claim 9 (original): The method according to claim 1, which further comprises forming the germination layer with interruptions in the profile provided for the conductor run.

Claim 10 (withdrawn): The method according to claim 1, which further comprises:

connecting a compensating layer to the motor vehicle molding in a floating manner; and

applying the conductor run partially on the compensating layer.

Claim 11 (currently amended): The method according to claim 1, which further comprises varying a material structure of the conductor run by using a thermal or pressure treatment.

Claim 12 (withdrawn): The method according to claim 1, which further comprises coating the conductor run after the conductor run is applied for at least one of increasing a conductivity and providing a protective layer.

Claim 13 (withdrawn): The method according to claim 1, which further comprises applying the conductor run such that an electrical functional component is produced.

Claim 14 (withdrawn): The method according to claim 1, which further comprises applying at least two conductor runs which are isolated from one another and are disposed one above another in layers.

Claim 15 (withdrawn): The method according to claim 1, which further comprises forming large-area conductive levels which are disposed in layers, the large-area conductive levels forming part of an electrical power supply system, and carry out different functions for the electrical power supply system.

Claim 16 (withdrawn): The method according to claim 1, which further comprises applying the conductor run such that it can be disconnected from the motor vehicle molding.

Claim 17 (withdrawn): The method according to claim 15, which further comprises applying a structure selected from the group consisting of an insulating layer and an insulating element before an application of the conductor run.

Claim 18 (withdrawn): The method according to claim 1, which further comprises applying an extension to the motor vehicle

molding, and applying the conductor run from the motor vehicle molding, extending to the extension, for forming a pigtail.

Claim 19 (withdrawn): The method according to claim 1, which further comprises placing one conductor end of a connecting conductor on the motor vehicle molding and the connecting conductor is electrically conductively connected to the conductor run when the conductor run is subsequently applied.

Claim 20 (withdrawn): The method according to claim 1, which further comprises:

fitting a plug molding to the motor vehicle molding; and

subsequently coating the plug molding, at least partially, with a piece of the conductor run, thus producing a contact plug.

Claim 21 (withdrawn): The method according to claim 1, which further comprises contacting the conductor run with a mount selected from the group consisting of a circuit mount having a contact element and a circuit mount assembly having a contact element, and the conductor run makes contact with the contact element.

Claim 22 (withdrawn): The method according to claim 2, wherein the conductor run produced by the beam thermal/kinetic application method makes contact with an electrical component.

Claim 23 (withdrawn): The method according to claim 1, which further comprises changing the motor vehicle molding to a desired final shape by a forming process after an application of the conductor run.

Claim 24 (withdrawn): The method according to claim 23, which further comprises dimensioning the conductor run in a forming area of the motor vehicle molding such that the conductor run has a desired electrical characteristics after the forming process of the motor vehicle molding.

Claim 25 (original): The method according to claim 2, which further comprises using a gas flame spraying process as the beam thermal/kinetic application method.

Claim 26 (withdrawn): The method according to claim 4, which further comprises using silicon as the nonconductive impurities.

Claim 27 (withdrawn): The method according to claim 1, which further comprises applying at least one further conductor run

to the germination layer and the conductor run and the further conductor run form an electrical functional component.

Claim 28 (cancelled).